

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	9165	(mold\$3 encapsulant resin epoxy) with (fiber fibrous) and (chip die ic) same (substrate board interposer carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/23 12:18
L3	1201	(mold\$3 encapsulant resin epoxy polymer) with (fiber fibrous) with filler and (chip die ic) same (substrate board interposer carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/23 13:32
L6	95	(mold\$3 encapsulant resin epoxy polymer) with (fiber fibrous) with filler same (length width) and (chip die ic) same (substrate board interposer carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/23 14:23